

N-TOPCon 主栅浆料 | GD127

N-TOPCon Busbar Ag pastes for B-Doped Emitter with LIF process

适用场景 Application	<ul style="list-style-type: none"> N 型电池正面主栅浆料 N-type front side busbar pastes N 型电池背面主栅浆料 N-type back side busbar pastes
亮点 Highlight	<ul style="list-style-type: none"> 适配 N-TOPCon 硼掺杂发射极、常规烧结及 LIF 激光工艺，也可结合客户端需求，单独设计针对性的浆料，匹配高速印刷及各种网版参数 Adapted to N-TOPCon B-doped emitter, conventional firing and LIF laser process. We can also customize targeted paste formulas according to customer requirements, suitable for high-speed printing and various screen mesh parameters. 针对性开发无机体系，减弱钝化层的损伤，可带来更高的 Uoc、FF 性能 Less damage on passivation layer better Uoc and FF 更宽的拉力窗口，更好的组件端焊接表现 Reliable and robust soldering window for module process 自主银粉，配方调整空间大，更宽的印刷性调整空间，可匹配更窄的主栅连接线 Own patented silver powders for better printability of busbar connecting lines

检测类型	检测方法	控制范围	单位
粘度	Bookfiled HB-DV2T, 52#转子@5 RPM, 25±0.1°C	40-130	Pa·S
细度	刮板细度计-2 th	≤13	μm
固含量	马弗炉	74-88	Wt,%

同一主栅图形下，不同固含主栅浆料的表现汇总：

Summary of the performance of different solids in the same grid pattern

